

DATA SHEET

NEC

GaAs INTEGRATED CIRCUIT μ PG2160T5K

L, S-BAND SPDT SWITCH

DESCRIPTION

The μ PG2160T5K is a GaAs MMIC for L, S-band SPDT (Single Pole Double Throw) switch which was developed for mobile phone and another L, S-band applications.

This device can operate frequency from 0.5 to 3.0 GHz, having the low insertion loss and high isolation.

This device is housed in a 6-pin plastic TSSON (Thin Shrink Small Out-line Non-leaded) package. And this package is able to high-density surface mounting.

FEATURES

- Supply voltage : $V_{DD} = 2.4$ to 2.8 V (2.6 V TYP.)
- Switch control voltage : $V_{cont(H)} = 2.4$ to V_{DD} (2.6 V TYP.)
: $V_{cont(L)} = -0.2$ to 0.2 V (0 V TYP.)
- Low insertion loss : $L_{ins1} = 0.30$ dB TYP. @ $f = 0.5$ to 1.0 GHz, $V_{DD} = 2.6$ V, $V_{cont(H)} = 2.6$ V, $V_{cont(L)} = 0$ V
: $L_{ins2} = 0.35$ dB TYP. @ $f = 1.0$ to 2.0 GHz, $V_{DD} = 2.6$ V, $V_{cont(H)} = 2.6$ V, $V_{cont(L)} = 0$ V
: $L_{ins3} = 0.40$ dB TYP. @ $f = 2.0$ to 2.5 GHz, $V_{DD} = 2.6$ V, $V_{cont(H)} = 2.6$ V, $V_{cont(L)} = 0$ V
: $L_{ins4} = 0.50$ dB TYP. @ $f = 2.5$ to 3.0 GHz, $V_{DD} = 2.6$ V, $V_{cont(H)} = 2.6$ V, $V_{cont(L)} = 0$ V
- High isolation : $ISL1 = 25$ dB TYP. @ $f = 0.5$ to 1.0 GHz, $V_{DD} = 2.6$ V, $V_{cont(H)} = 2.6$ V, $V_{cont(L)} = 0$ V
: $ISL2 = 18$ dB TYP. @ $f = 1.0$ to 2.0 GHz, $V_{DD} = 2.6$ V, $V_{cont(H)} = 2.6$ V, $V_{cont(L)} = 0$ V
: $ISL3 = 17$ dB TYP. @ $f = 2.0$ to 2.5 GHz, $V_{DD} = 2.6$ V, $V_{cont(H)} = 2.6$ V, $V_{cont(L)} = 0$ V
: $ISL4 = 13$ dB TYP. @ $f = 2.5$ to 3.0 GHz, $V_{DD} = 2.6$ V, $V_{cont(H)} = 2.6$ V, $V_{cont(L)} = 0$ V
- Handling power : $P_{in(0.1dB)} = +21.0$ dBm TYP. @ $f = 2.0/2.5$ GHz, $V_{DD} = 2.6$ V, $V_{cont(H)} = 2.6$ V, $V_{cont(L)} = 0$ V
- High-density surface mounting : 6-pin plastic TSSON package ($1.0 \times 1.0 \times 0.37$ mm)

APPLICATIONS

- L, S-band digital cellular or cordless telephone
- W-LAN, WLL and Bluetooth™ etc.

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
μ PG2160T5K-E2	μ PG2160T5K-E2-A	6-pin plastic TSSON (Pb-Free) ^{Note}	G4	<ul style="list-style-type: none"> • Embossed tape 8 mm wide • Pin 1, 6 face the perforation side of the tape • Qty 5 kpcs/reel

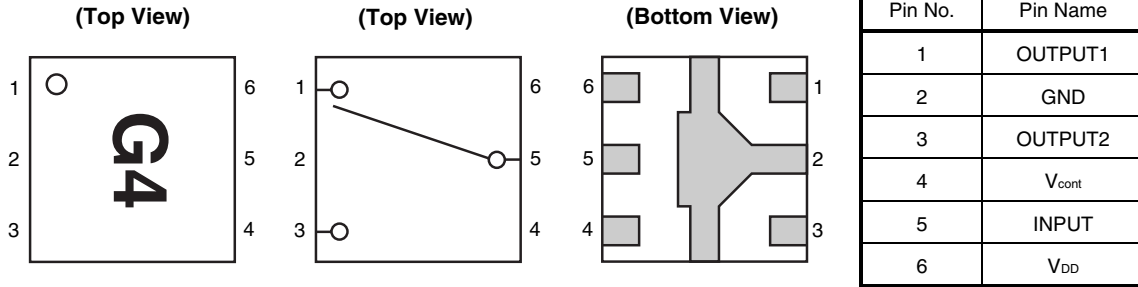
Note With regards to terminal solder (the solder contains lead) plated products (conventionally plated), contact your nearby sales office.

Remark To order evaluation samples, contact your nearby sales office.
Part number for sample order: μ PG2160T5K

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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Not all products and/or types are available in every country. Please check with an NEC Electronics sales representative for availability and additional information.

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



TRUTH TABLE

V _{cont}	INPUT-OUTPUT1	INPUT-OUTPUT2
High	OFF	ON
Low	ON	OFF

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V _{DD}	+6.0	V
Switch Control Voltage	V _{cont}	+6.0	V
Input Power	P _{in}	+26	dBm
Operating Ambient Temperature	T _A	-45 to +85	°C
Storage Temperature	T _{stg}	-55 to +135	°C

RECOMMENDED OPERATING RANGE (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage ^{Note}	V _{DD}	2.4	2.6	2.8	V
Switch Control Voltage (H) ^{Note}	V _{cont (H)}	2.4	2.6	V _{DD}	V
Switch Control Voltage (L)	V _{cont (L)}	-0.2	0	0.2	V

Note V_{cont (H)} ≤ V_{DD}

ELECTRICAL CHARACTERISTICS

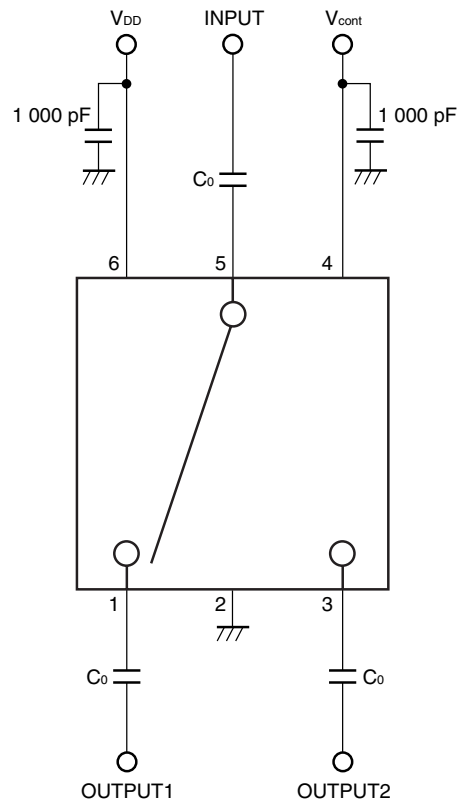
(T_A = +25°C, V_{DD} = 2.6 V, V_{cont} (H) = 2.6 V, V_{cont} (L) = 0 V, DC cut capacitors = 56 pF, unless otherwise specified)

Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	L _{ins1}	f = 0.5 to 1.0 GHz	–	0.30	0.45	dB
Insertion Loss 2	L _{ins2}	f = 1.0 to 2.0 GHz	–	0.35	0.50	
Insertion Loss 3	L _{ins3}	f = 2.0 to 2.5 GHz	–	0.40	0.55	
Insertion Loss 4	L _{ins4}	f = 2.5 to 3.0 GHz	–	0.50	0.65	
Isolation 1	ISL1	f = 0.5 to 1.0 GHz	22	25	–	dB
Isolation 2	ISL2	f = 1.0 to 2.0 GHz	15	18	–	
Isolation 3	ISL3	f = 2.0 to 2.5 GHz	14	17	–	
Isolation 4	ISL4	f = 2.5 to 3.0 GHz	10	13	–	
Input Return Loss	RL _{in}	f = 0.5 to 3.0 GHz	15	20	–	dB
Output Return Loss	RL _{out}	f = 0.5 to 3.0 GHz	15	20	–	dB
0.1 dB Loss Compression Input Power ^{Note}	P _{in (0.1 dB)}	f = 2.0/2.5 GHz	+18.0	+21.0	–	dBm
2nd Harmonics	2f ₀	f = 2.0/2.5 GHz, P _{in} = +10 dBm	65	75	–	dBc
3rd Harmonics	3f ₀	f = 2.0/2.5 GHz, P _{in} = +10 dBm	65	75	–	dBc
Supply Current	I _{DD}	No signal	–	50	100	μA
Switch Control Current	I _{cont}		–	4	20	μA
Switch Control Speed	t _{sw}	50% CTL to 90/10% RF	–	150	–	ns

Note P_{in (0.1 dB)} is measured the input power level when the insertion loss increases more 0.1 dB than that of linear range.

Caution This device is used it is necessary to use DC cut capacitors.

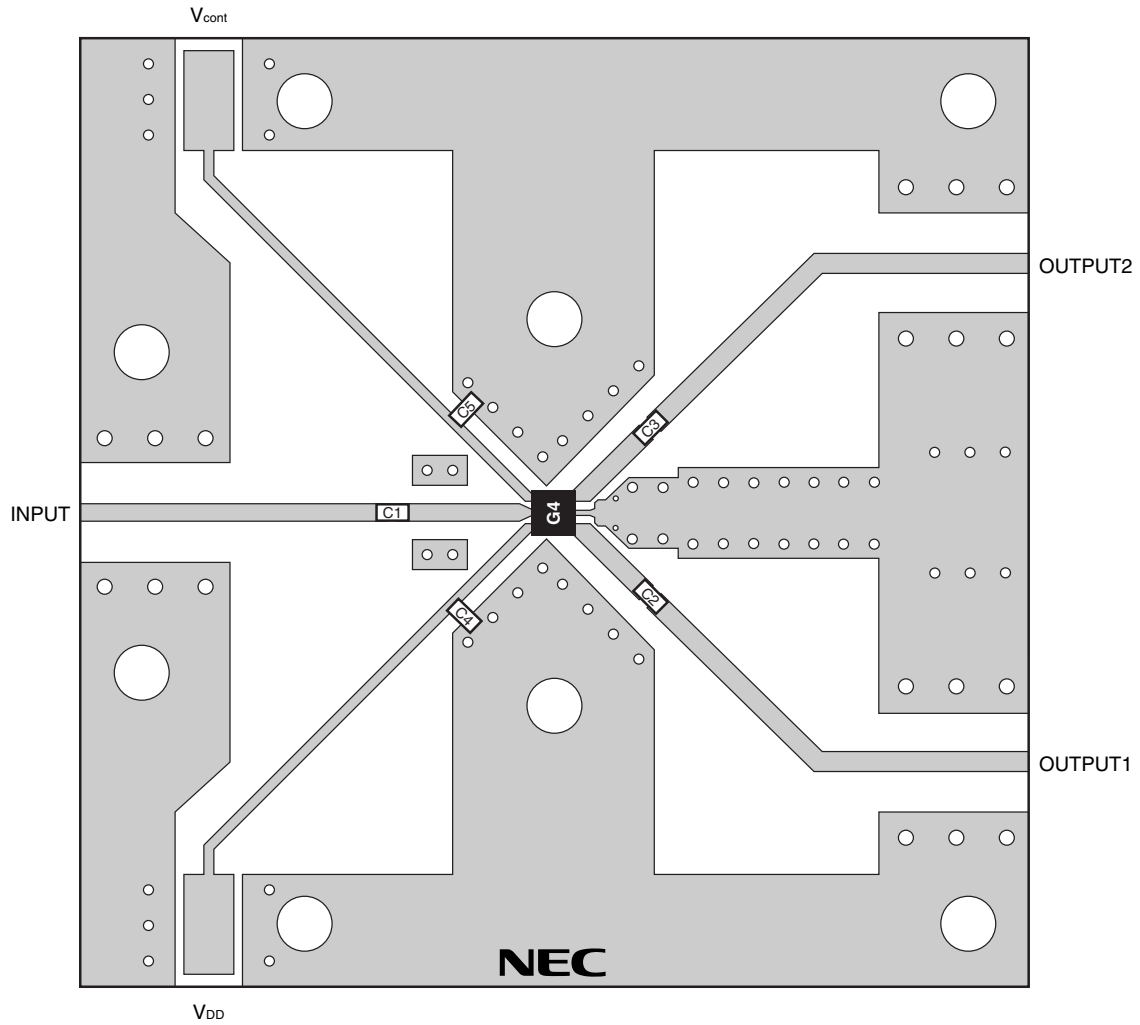
EVALUATION CIRCUIT



Remark C₀ : 56 pF

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

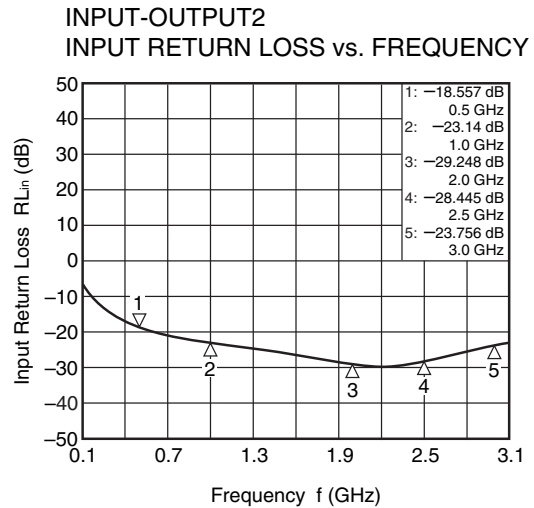
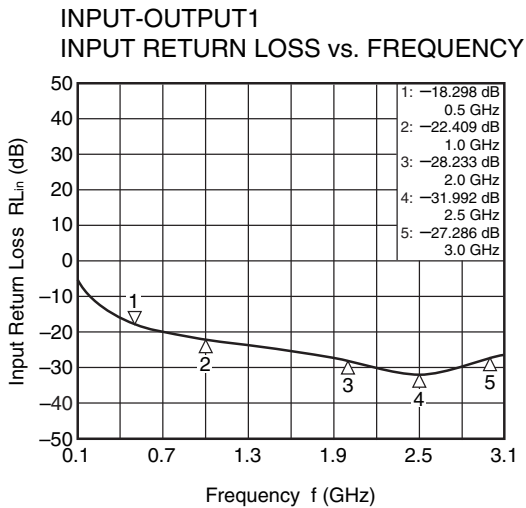
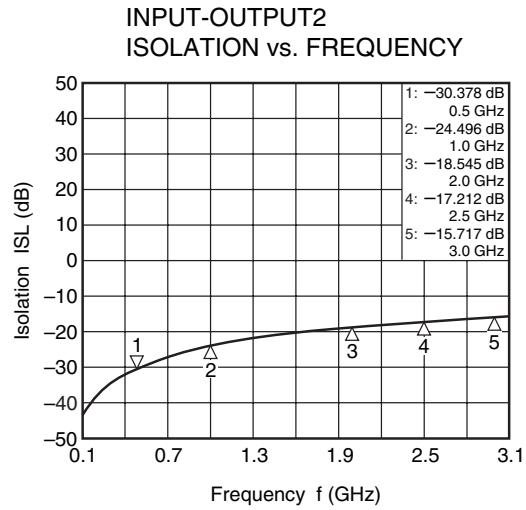
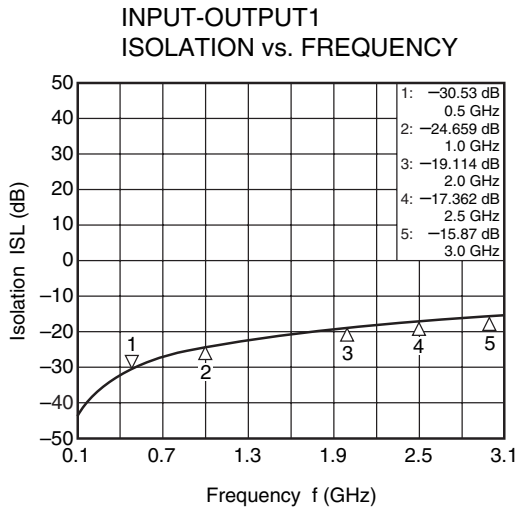
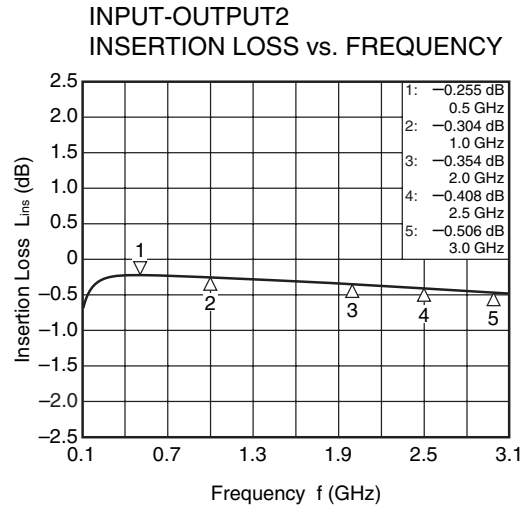
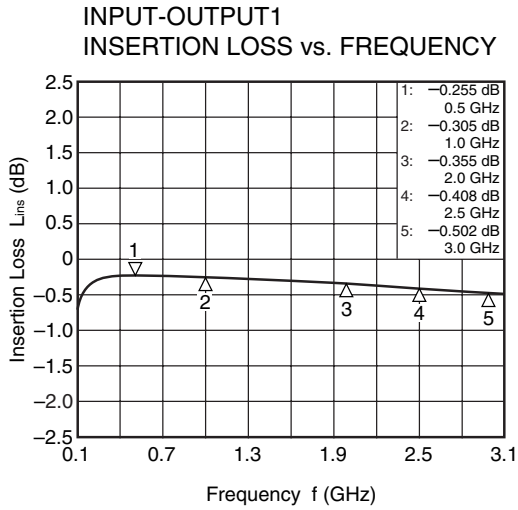
ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD



USING THE NEC EVALUATION BOARD

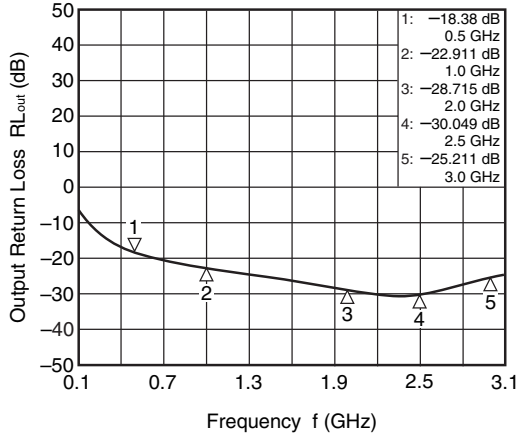
Symbol	Values
C1, C2, C3	56 pF
C4, C5	1 000 pF

TYPICAL CHARACTERISTICS (T_A = +25°C, V_{DD} = 2.6 V, V_{cont} (H) = 2.6 V, V_{cont} (L) = 0 V, DC cut capacitors = 56 pF, using test fixture, unless otherwise specified)

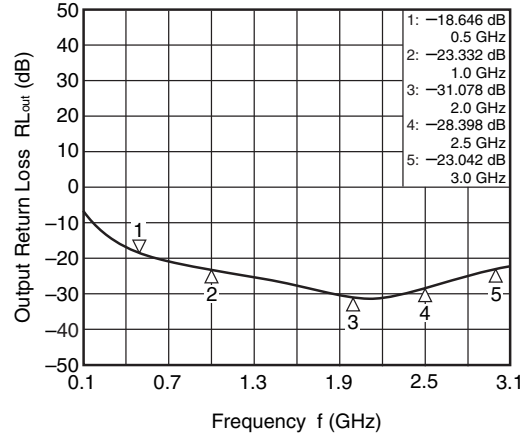


Remark The graphs indicate nominal characteristics.

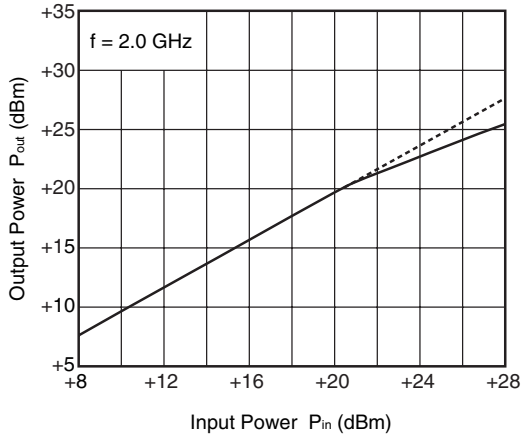
INPUT-OUTPUT1
OUTPUT RETURN LOSS vs. FREQUENCY



INPUT-OUTPUT2
OUTPUT RETURN LOSS vs. FREQUENCY



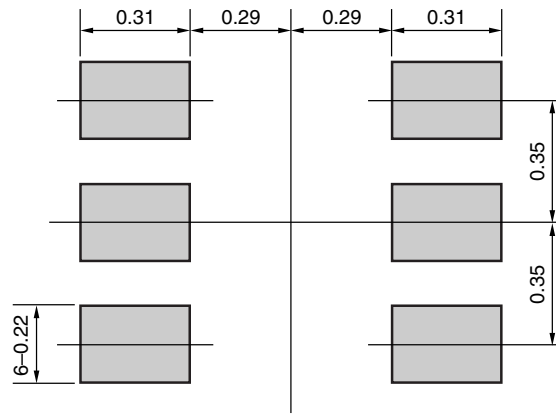
OUTPUT POWER vs. INPUT POWER



Remark The graphs indicate nominal characteristics.

MOUNTING PAD DIMENSIONS

6-PIN PLASTIC TSSOP (UNIT: mm)

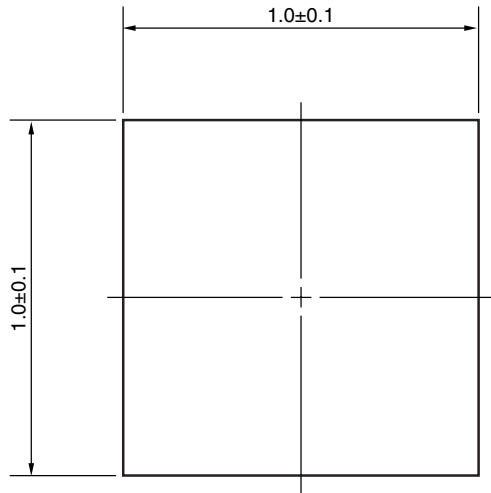


Remark The mounting pad layouts in this document are for reference only.

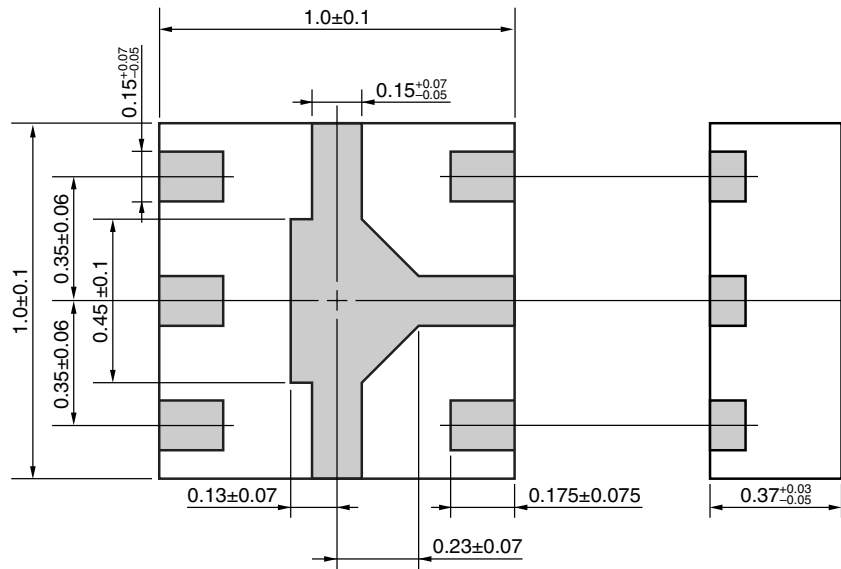
PACKAGE DIMENSIONS

6-PIN PLASTIC TSSOP (UNIT: mm)

(Top View)



(Bottom View)



RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature)	: 260°C or below
	Time at peak temperature	: 10 seconds or less
	Time at temperature of 220°C or higher	: 60 seconds or less
	Preheating time at 120 to 180°C	: 120±30 seconds
	Maximum number of reflow processes	: 3 times
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below
Wave Soldering	Peak temperature (molten solder temperature)	: 260°C or below
	Time at peak temperature	: 10 seconds or less
	Preheating temperature (package surface temperature)	: 120°C or below
	Maximum number of flow processes	: 1 time
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below
Partial Heating	Peak temperature (terminal temperature)	: 350°C or below
	Soldering time (per side of device)	: 3 seconds or less
	Maximum chlorine content of rosin flux (% mass)	: 0.2%(Wt.) or below

Caution Do not use different soldering methods together (except for partial heating).

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M8E 02.11-1

Caution	GaAs Products	<p>This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.</p> <ul style="list-style-type: none"> • Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below. <ol style="list-style-type: none"> 1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials. 2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal. • Do not burn, destroy, cut, crush, or chemically dissolve the product. • Do not lick the product or in any way allow it to enter the mouth.
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► For further information, please contact

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